

# **[HIGH DENSITY LAMINATED SUBSTRATE STRUCTURE AND MANUFACTURE METHOD THEREOF]**

## **Abstract of Disclosure**

A laminated substrate structure composed of a plurality of dielectric layers and a plurality of circuit layers stacked with each other. Each of the dielectric layers has a plurality of via studs, and the circuit layers are electrically coupled with each other through the via studs. The laminated substrate structure of the present invention is characterized by adopting the embedded structure landless design that provides high reliability and better adherence. The present invention also provides a laminated substrate manufacture method. The dielectric layers having the patterned circuit and the dielectric layers having the via holes are formed first, and after the dielectric layers having the patterned circuit and the dielectric layers having the via holes are formed, they are aligned and laminated synchronously to complete the manufacture of the laminated substrate.

## Figures